

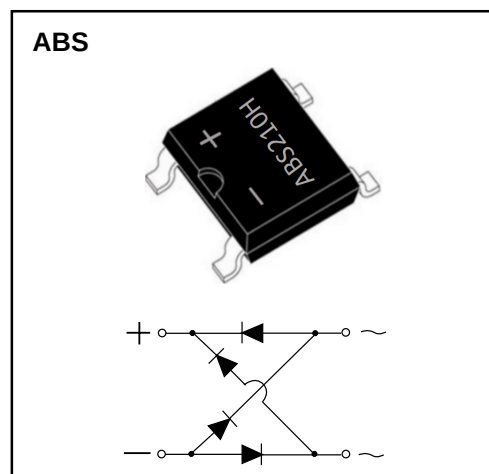
ABS Plastic-Encapsulate Bridge Rectifier

Features

- I_o 2.0A
- VRRM 200V-1000V
- Low forward voltage drop
- High surge current capability
- Glass passivated chip junction

Mechical Data

- Case: ABS molded plastic
- Molding compound: UL flammability classification rating 94V-0
- Terminals: Solder plated, solderable per MIL- STD-202, Method 208
- Polarity: As marked on case



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	ABS2				
				02H	04H	06H	08H	10H
Repetitive Peak Reverse Voltage	V_{RRM}	V		200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		140	280	420	560	700
Maximum DC blocking Voltage	V_{DC}	V		200	400	600	800	1000
Average Rectified Output Current	I_o	A	60Hz sine wave, R-load, $T_a=40^{\circ}\text{C}$	2.0				
Surge(Non-repetitive)Forward Current	I_{FSM}	A	8.3ms half sine wave, 1 cycle, $T_j=25^{\circ}\text{C}$	70				
Current Squared Time	I^2t	A^2S	$1\text{ms} \leq t < 8.3\text{ms}$ $T_j=25^{\circ}\text{C}$, Rating of per diode	20.3				
Storage Temperature	T_{stg}	$^{\circ}\text{C}$		-55 ~ +150				
Junction Temperature	T_j	$^{\circ}\text{C}$		-55 ~ +150				

Electrical Characteristics ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	$I_{FM}=2.0\text{A}$, Pulse measurement, Rating of per diode	1.2
Peak Reverse Current	I_{RRM1}	μA	Maximum DC reverse current $T_A=25^{\circ}\text{C}$	5
	I_{RRM2}	μA	at rated DC blocking voltage $T_A=125^{\circ}\text{C}$	500
Thermal Resistance	$R_{\theta J-A}$	$^{\circ}\text{C}/\text{W}$	Between junction and ambient, On alumina substrate	62.5
	$R_{\theta J-C}$		Between junction and case	20
	$R_{\theta J-L}$		Between junction and lead	25

Typical Characteristics

FIG1: I_o - T_a Curve

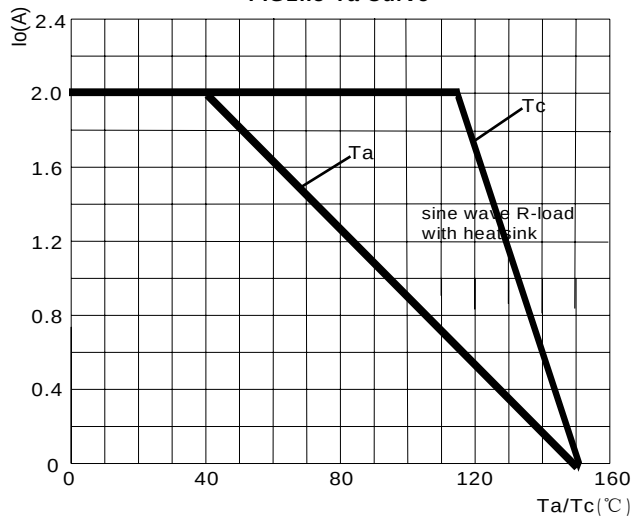


FIG2: Surge Forward Current Capability

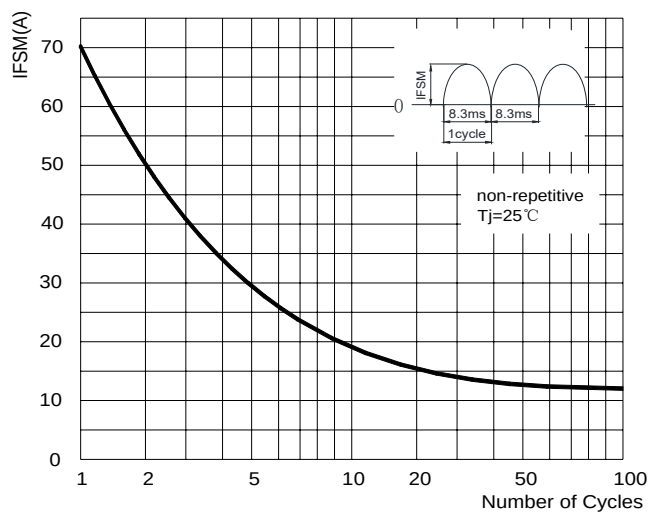


FIG3: Forward Voltage

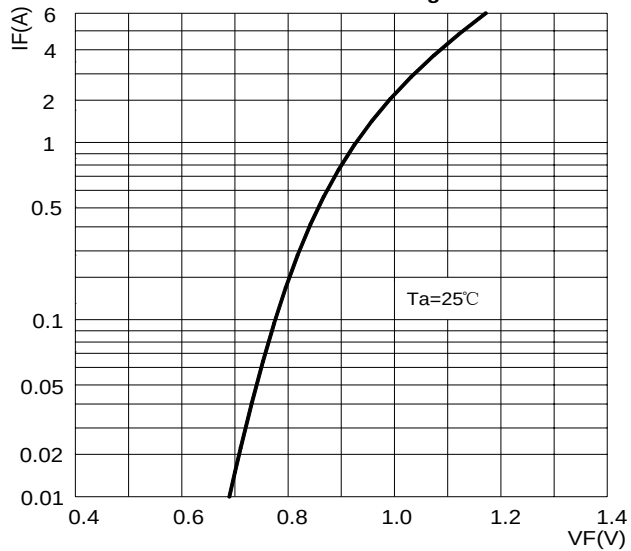
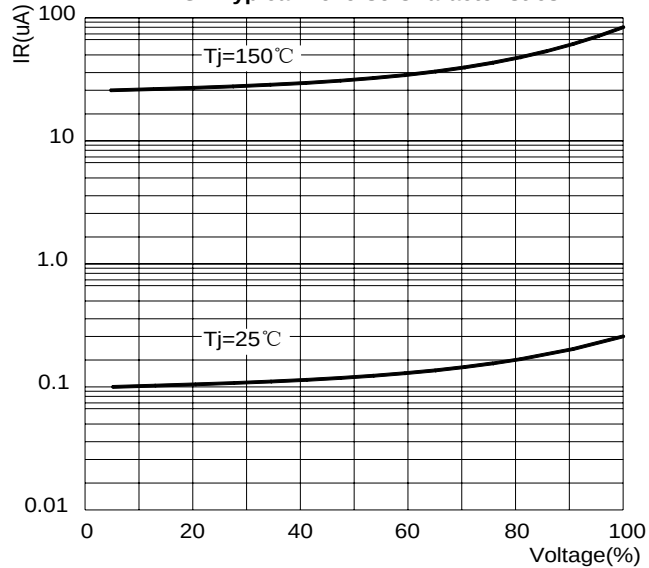
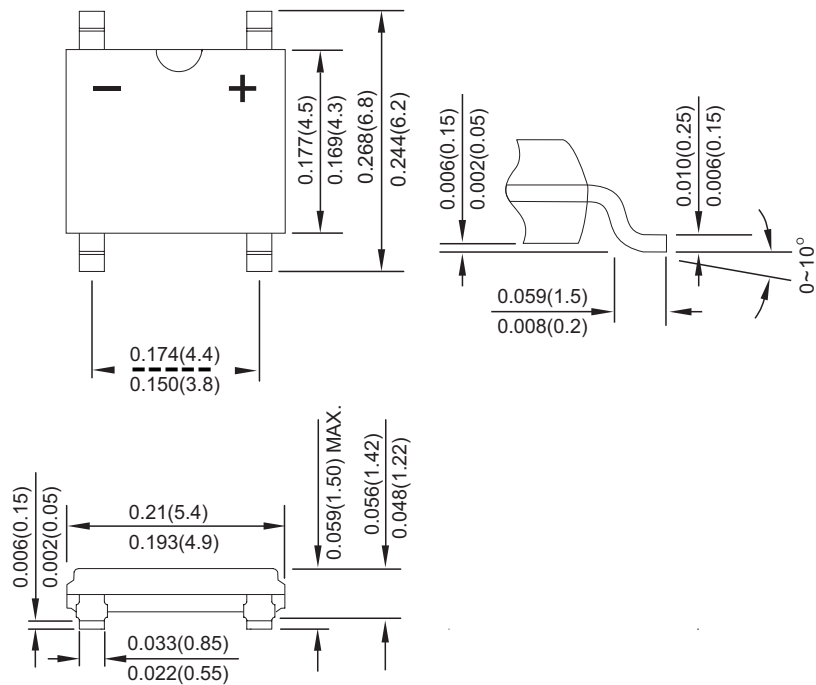


FIG4: Typical Reverse Characteristics

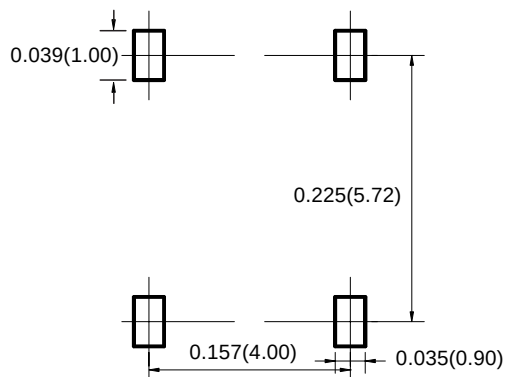


ABS Package Outline Dimensions



Dimensions in inches and (millimeters)

ABS Suggested Pad Layout



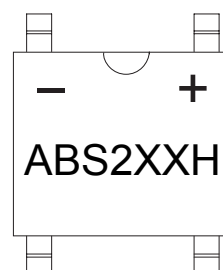
Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

Ordering Information

Part Number	Package	Shipping Quantity
ABS202H- ABS210H	ABS	3000/tape&Reel

Marking Diagram



XX: From 02 to 10

Reel Taping Specifications For Surface Mount Devices–ABS

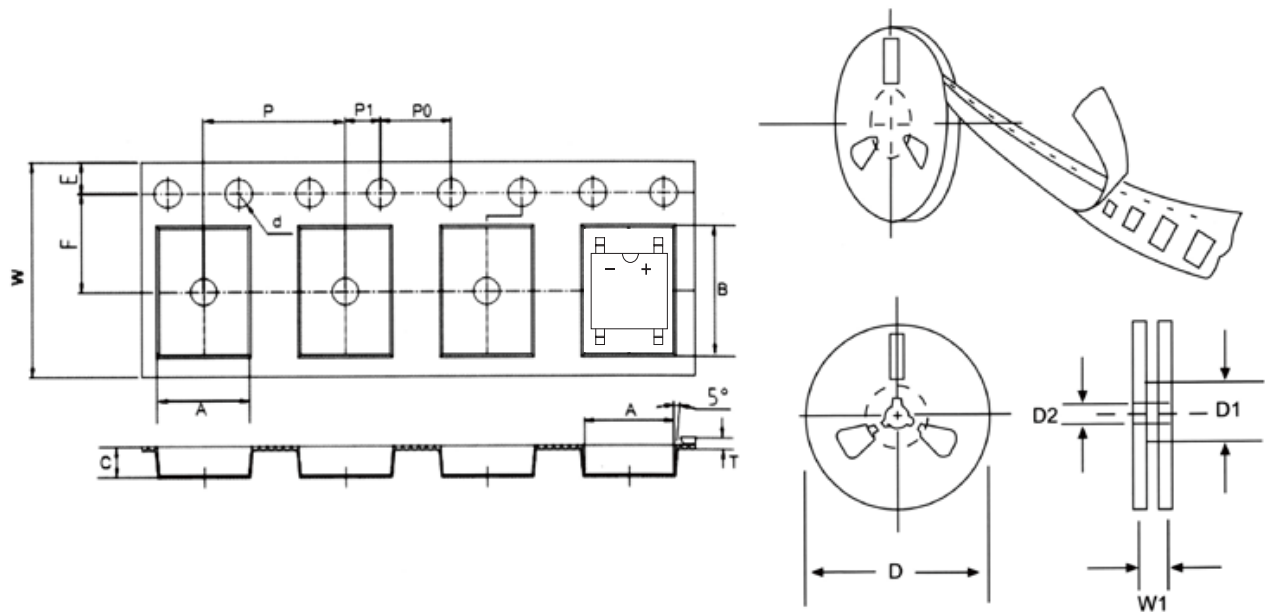


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	ABS mm(inch)
Carrier width	A	5.40±0.1(0.213±0.004)
Carrier length	B	6.90±0.05(0.272±0.002)
Carrier depth	C	2.10±0.1(0.083±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.10-0.70(0.004-0.028)
Tape width	W	12.0±0.3/-0.1(0.472±0.004)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packde in accordance with EIA standard RS-481-A and specification given above.